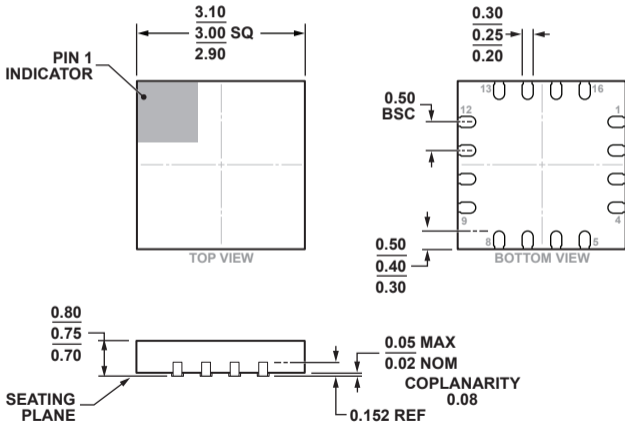


Bill Of Materials (BOM)

MATERIAL	FROM:	TO:	REMARKS
Die Attach Film	Ablestik 8006NS	Ablestik ATB-125	From screen print to DAF
Wire	2N Gold 0.8mil	2N Gold 0.8mil	Same
Mold Compound	Sumitomo G700	Sumitomo G700LA	Same base material
Leadframe	C7025	C7025	Same; Roughened Cu

**16-Lead Lead Frame Chip Scale Package [LFCSP_WQ]
3 x 3 mm Body, Very Very Thin Quad
(CP-16-32)**

Dimensions shown in millimeters



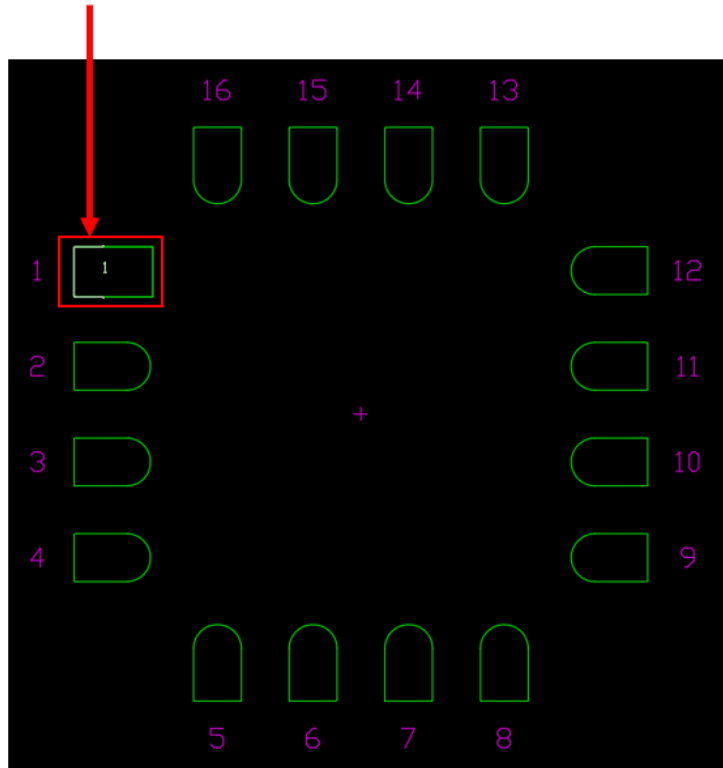
COMPLIANT TO JEDEC STANDARDS MO-220-WEED.

Pin 1 Identifier

FROM :

TO :

Pin 1 Identifier – Rectangular Shape different from other Leads



Pin 1 Identifier – Chamfer Shape different from other Leads

